

## Description

Atmel® ATWINC1500B is a single chip IEEE® 802.11 b/g/n Radio/Baseband/MAC network controller optimized for low-power mobile applications. ATWINC1500B supports single stream 1x1 802.11n mode providing up to 72Mbps PHY rate. ATWINC1500B features fully integrated Power Amplifier, LNA, Switch, and Power Management. ATWINC1500B also features an on-chip microcontroller and integrated Flash memory for system software. Implemented in 65nm CMOS technology, the ATWINC1500B offers very low power consumption while simultaneously providing high performance and minimal bill of materials.

The ATWINC1500B supports 2- and 3-wire Bluetooth® coexistence protocols. The ATWINC1500B provides multiple peripheral interfaces including UART, SPI, I<sup>2</sup>C the only external clock source needed for the ATWINC1500B is a high-speed crystal or oscillator with a wide range of reference clock frequencies supported (12-40MHz). The ATWINC1500B is available in QFN packaging.

## Features

- IEEE 802.11 b/g/n 20MHz (1x1) solution
- Single spatial stream in 2.4GHz ISM band
- Integrated PA and T/R Switch
- Superior Sensitivity and Range via advanced PHY signal processing
- Advanced Equalization and Channel Estimation
- Advanced Carrier and Timing Synchronization
- Wi-Fi Direct and Soft-AP support
- Supports IEEE 802.11 WEP, WPA, and WPA2 Security
- Supports China WAPI security
- Superior MAC throughput via hardware accelerated two-level A-MSDU/A-MPDU frame aggregation and block acknowledgement
- On-chip memory management engine to reduce host load
- Integrated Flash memory for system software
- SPI, UART, and I<sup>2</sup>C host interfaces
- 2- or 3-wire Bluetooth coexistence interface
- Operating temperature range of -40°C to +85°C
- Power save modes:
  - <4μA Power Down mode typical @3.3V I/O

- 380uA Doze mode with chip settings preserved (used for beacon monitoring)
  - On-chip low power sleep oscillator
  - Fast host wake-up from Doze mode by a pin or host I/O transaction
- Fast boot options:
  - On-Chip Boot ROM (firmware instant boot)
  - SPI Flash boot (firmware patches and state variables)
  - Low-leakage on-chip memory for state variables
  - Fast AP re-association (150ms)
- On-Chip Network Stack to offload MCU:
  - Integrated Network IP stack to minimize host CPU requirements
  - Network features: TCP, UDP, DHCP, ARP, HTTP, SSL, and DNS
- Hardware accelerators for Wi-Fi and SSL security to improve connection time
- Hardware accelerator for IP checksum
- Hardware accelerators for OTA security

## Table of Contents

|          |  |           |
|----------|--|-----------|
| <b>1</b> | <b>Ordering Information and IC Marking</b>         | <b>5</b>  |
| <b>2</b> | <b>Block Diagram</b>                               | <b>5</b>  |
| <b>3</b> | <b>Pinout and Package Information</b>              | <b>6</b>  |
| 3.1      | Pin Description                                    | 6         |
| 3.2      | Package Description                                | 8         |
| <b>4</b> | <b>Electrical Specifications</b>                   | <b>9</b>  |
| 4.1      | Absolute Ratings                                   | 9         |
| 4.2      | Recommended Operating Conditions                   | 9         |
| 4.3      | DC Electrical Characteristics                      | 10        |
| <b>5</b> | <b>Clocking</b>                                    | <b>10</b> |
| 5.1      | Crystal Oscillator                                 | 10        |
| 5.2      | Low Power Oscillator                               | 11        |
| <b>6</b> | <b>CPU and Memory Subsystems</b>                   | <b>12</b> |
| 6.1      | Processor  | 12        |
| 6.2      | Memory Subsystem                                   | 12        |
| 6.3      | Non-volatile Memory (eFuse)                        | 12        |
| <b>7</b> | <b>WLAN Subsystem</b>                              | <b>13</b> |
| 7.1      | MAC  | 13        |
| 7.1.1    | Features   | 13        |
| 7.1.2    | Description  | 13        |
| 7.2      | PHY  | 14        |
| 7.2.1    | Features   | 14        |
| 7.2.2    | Description  | 14        |
| 7.3      | Radio  | 14        |
| 7.3.1    | Receiver Performance                               | 14        |
| 7.3.2    | Transmitter Performance                            | 16        |
| <b>8</b> | <b>External Interfaces</b>                         | <b>17</b> |
| 8.1      | I <sup>2</sup> C Slave Interface                   | 17        |
| 8.2      | I <sup>2</sup> C Master Interface                  | 19        |
| 8.3      | SPI Slave Interface                                | 19        |
| 8.4      | UART   | 22        |
| 8.5      | Wi-Fi/Bluetooth Coexistence                        | 23        |
| 8.6      | GPIOs  | 23        |
| <b>9</b> | <b>Power Management</b>                            | <b>24</b> |
| 9.1      | Power Architecture                                 | 24        |
| 9.2      | Power Consumption                                  | 25        |
| 9.2.1    | Description of Device States                       | 25        |
| 9.2.2    | Current Consumption in Various Device States       | 25        |
| 9.2.3    | Restrictions for Power States                      | 26        |
| 9.3      | Power-Up/Down Sequence                             | 26        |
| 9.4      | Digital I/O Pin Behavior during Power-Up Sequences | 28        |

|           |   |           |
|-----------|---|-----------|
| <b>10</b> | <b>Reference Design .....</b>                   | <b>29</b> |
| 10.1      | Reference Schematic .....                       | 29        |
| 10.2      | Reference BOM .....                             | 30        |
| <b>11</b> | <b>Reflow Profile Information .....</b>         | <b>31</b> |
| 11.1      | Storage Condition.....                          | 31        |
| 11.1.1    | Moisture Barrier Bag Before Opened .....        | 31        |
| 11.1.2    | Moisture Barrier Bag Open .....                 | 31        |
| 11.2      | Stencil Design .....                            | 31        |
| 11.3      | Baking Conditions .....                         | 31        |
| 11.4      | Soldering and Reflow Condition .....            | 31        |
| 11.4.1    | Reflow Oven .....                               | 31        |
| <b>12</b> | <b>Reference Documentation and Support.....</b> | <b>33</b> |
| 12.1      | Reference Documents.....                        | 33        |
| <b>13</b> | <b>Revision History .....</b>                   | <b>34</b> |

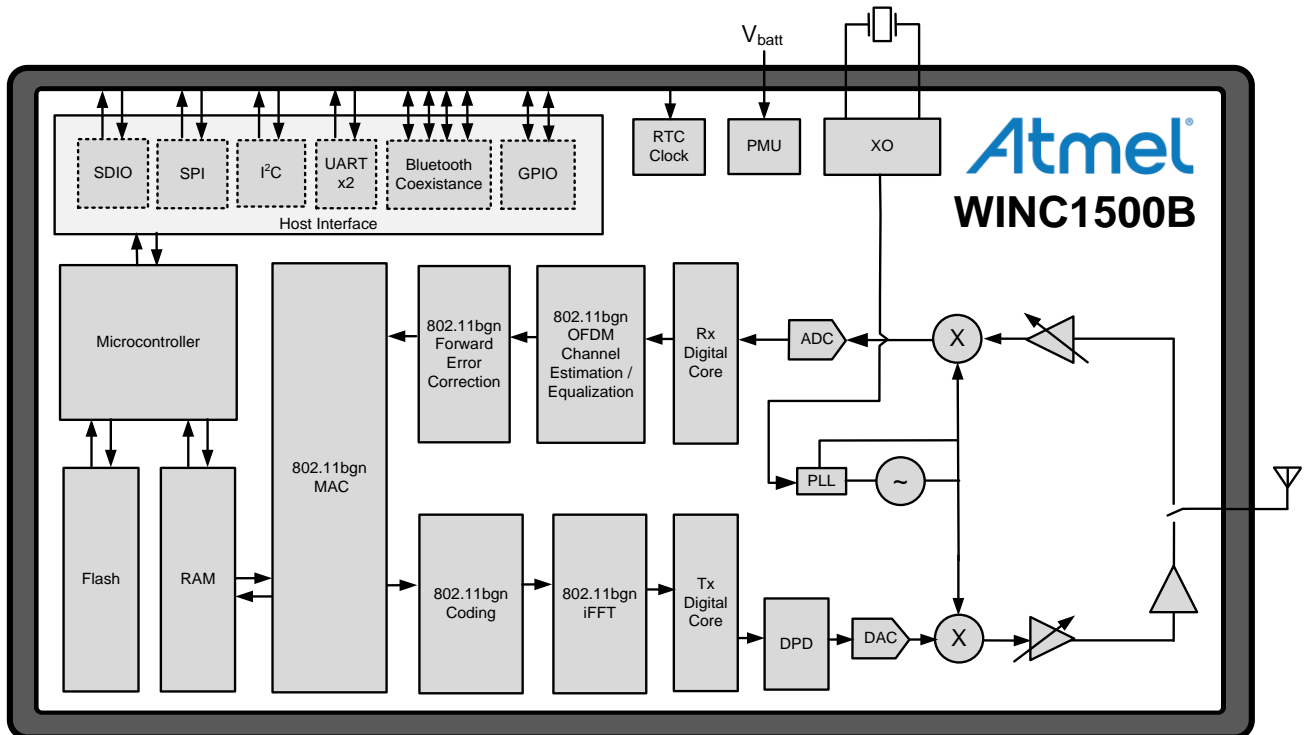
# 1 Ordering Information and IC Marking

Table 1-1. Ordering Details

| Atmel official part number (for ordering) | Package Type             | IC Marking  |
|---|--------------------------|-------------|
| ATWINC1500B-MU                            | 5x5 QFN in Tape and Reel | ATWINC1500B |

# 2 Block Diagram

Figure 2-1. ATWINC1500B Block Diagram



## 3 Pinout and Package Information

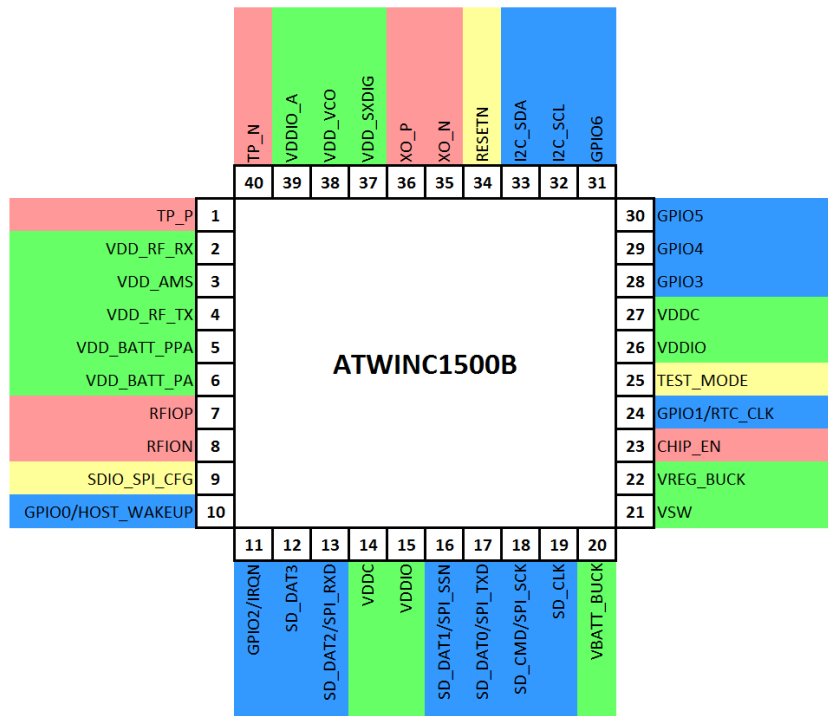
### 3.1 Pin Description

ATWINC1500B is offered in an exposed pad 40-pin QFN package. This package has an exposed paddle that must be connected to the system board ground. The QFN package pin assignment is shown in [Figure 3-1](#). The color shading is used to indicate the pin type as follows:

- Green – power
- Red – analog
- Blue – digital I/O
- Yellow – digital input
- Grey – unconnected or reserved

The ATWINC1500B pins are described in [Table 3-1](#).

**Figure 3-1. Pin Assignment**



**Table 3-1. Pin Description**

| Pin # | Pin Name     | Pin Type | Description                           |
|-------|--------------|----------|---------------------------------------|
| 1     | TP_P         | Analog   | Test Pin/Customer No Connect          |
| 2     | VDD_RF_RX    | Power    | Tuner RF Supply (see Section 9.1)     |
| 3     | VDD_AMS      | Power    | Tuner BB Supply (see Section 9.1)     |
| 4     | VDD_RF_TX    | Power    | Tuner RF Supply (see Section 9.1)     |
| 5     | VDD_BATT_PPA | Power    | PA 1st Stage Supply (see Section 9.1) |
| 6     | VDD_BATT_PA  | Power    | PA 2nd Stage Supply (see Section 9.1) |

| Pin # | Pin Name        | Pin Type                          | Description  |
|-------|-----------------|-----------------------------------|--|
| 7     | RFIOP           | Analog                            | Pos RF Differential I/O                                      |
| 8     | RFION           | Analog                            | Neg. RF Differential I/O                                     |
| 9     | SDIO_SPI_CFG    | Digital Input                     | Tie to 1 for SPI, 0 for SDIO                                 |
| 10    | GPIO0/HOST_WAKE | Digital I/O, Programmable Pull-Up | GPIO0/SLEEP Mode Control                                     |
| 11    | GPIO2/IRQN      | Digital I/O, Programmable Pull-Up | GPIO2/Device Interrupt                                       |
| 12    | SD_DAT3         | Digital I/O, Programmable Pull-Up | SDIO Data3   |
| 13    | SD_DAT2/SPI_RXD | Digital I/O, Programmable Pull-Up | SDIO Data2/SPI Data RX                                       |
| 14    | VDDC            | Power                             | Digital Core Power Supply (see Section 9.1)                  |
| 15    | VDDIO           | Power                             | Digital I/O Power Supply (see Section 9.1)                   |
| 16    | SD_DAT1/SPI_SSN | Digital I/O, Programmable Pull-Up | SDIO Data1/SPI Slave Select                                  |
| 17    | SD_DAT0/SPI_TXD | Digital I/O, Programmable Pull-Up | SDIO Data0/SPI Data TX                                       |
| 18    | SD_CMD/SPI_SCK  | Digital I/O, Programmable Pull-Up | SDIO Command/SPI Clock                                       |
| 19    | SD_CLK          | Digital I/O, Programmable Pull-Up | SDIO Clock   |
| 20    | VBATT_BUCK      | Power                             | Battery Supply for DC/DC Converter (see Section 9.1)         |
| 21    | VSW             | Power                             | Switching output of DC/DC Converter (see Section 9.1)        |
| 22    | VREG_BUCK       | Power                             | Core Power from DC/DC Converter (see Section 9.1)            |
| 23    | CHIP_EN         | Analog                            | PMU Enable   |
| 24    | GPIO1/RTC_CLK   | Digital I/O, Programmable Pull-Up | GPIO1/32kHz Clock Input                                      |
| 25    | TEST_MODE       | Digital Input                     | Test Mode – Customer Tie to GND                              |
| 26    | VDDIO           | Power                             | Digital I/O Power Supply (see Section 9.1)                   |
| 27    | VDDC            | Power                             | Digital Core Power Supply (see Section 9.1)                  |
| 28    | GPIO3           | Digital I/O, Programmable Pull-Up | GPIO3  |
| 29    | GPIO4           | Digital I/O, Programmable Pull-Up | GPIO4  |
| 30    | GPIO5           | Digital I/O, Programmable Pull-Up | GPIO5  |
| 31    | GPIO6           | Digital I/O, Programmable Pull-Up | GPIO6  |
| 32    | I2C_SCL         | Digital I/O, Programmable Pull-Up | I <sup>2</sup> C Slave Clock (high-drive pad, see Table 4-3) |
| 33    | I2C_SDA         | Digital I/O, Programmable Pull-Up | I <sup>2</sup> C Slave Data (high-drive pad, see Table 4-3)  |
| 34    | RESETN          | Digital Input                     | Active-Low Hard Reset  |
| 35    | XO_N            | Analog                            | Crystal Oscillator N   |
| 36    | XO_P            | Analog                            | Crystal Oscillator P   |
| 37    | VDD_SXDIG       | Power                             | SX Power Supply (see Section 9.1)                            |
| 38    | VDD_VCO         | Power                             | VCO Power Supply (see Section 9.1)                           |
| 39    | VDDIO_A         | Power                             | Tuner VDDIO Power Supply (see Section 9.1)                   |
| 40    | TP_N            | Analog                            | Test Pin/Customer No Connect                                 |
| 41    | PADDLE VSS      | Power                             | Connect to System Board Ground                               |

## 3.2 Package Description

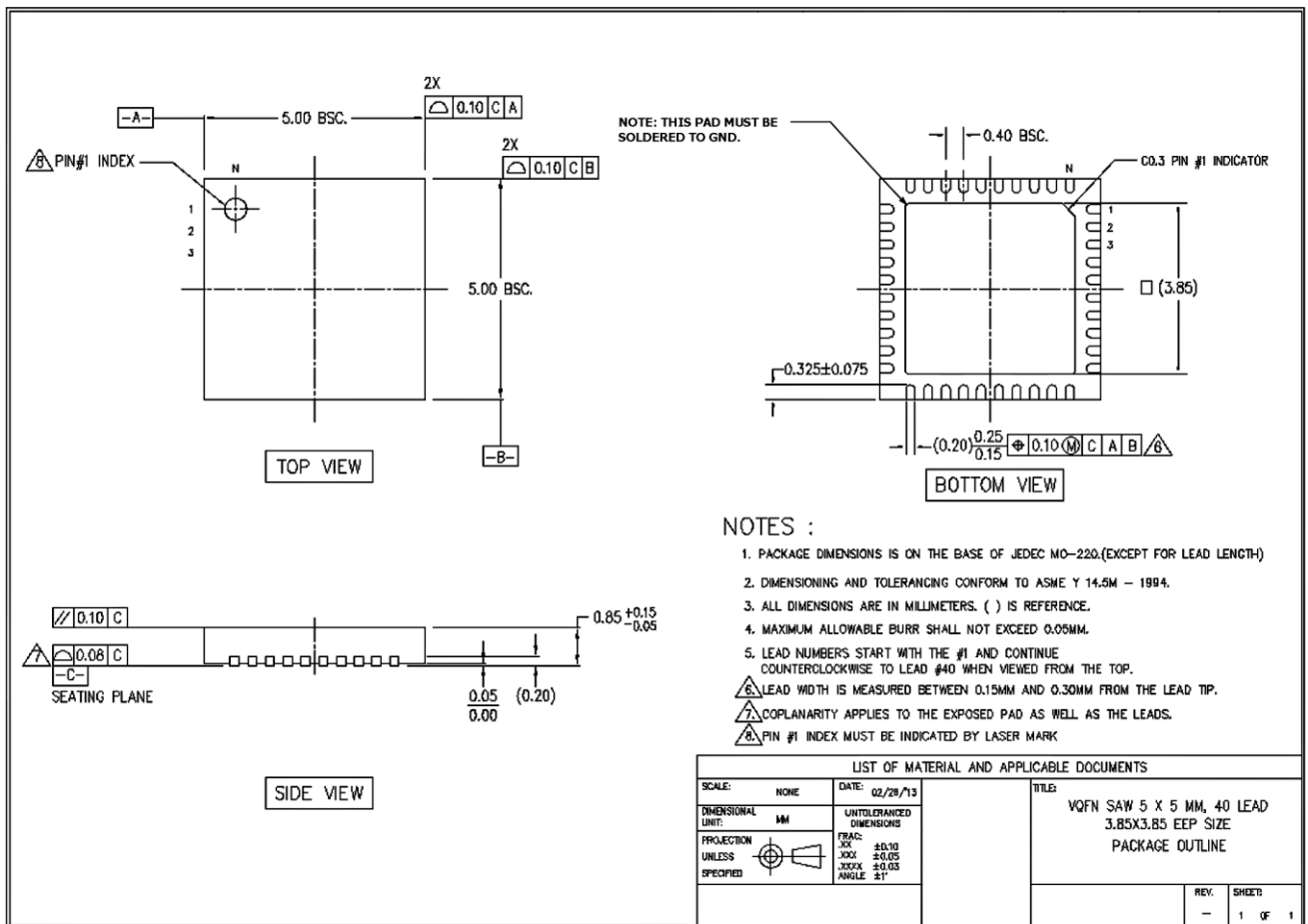
The ATWINC1500B QFN package information is provided in [Table 3-2](#).

**Table 3-2. QFN Package Information**

| Parameter        | Value   | Units | Tolerance |
|------------------|---------|-------|-----------|
| Package Size     | 5x5     | mm    | ±0.1mm    |
| QFN Pad Count    | 40      |       |           |
| Total Thickness  | 0.85    |       | ±0.05mm   |
| QFN Pad Pitch    | 0.40    | mm    |           |
| Pad Width        | 0.20    |       |           |
| Exposed Pad size | 3.7x3.7 | mm    |           |

The ATWINC1500B 40L QFN package view is shown in [Figure 3-2](#).

**Figure 3-2. QFN Package**



The QFN package is a qualified Green Package.



## 4 Electrical Specifications

### 4.1 Absolute Ratings

Table 4-1. Absolute Maximum Ratings

| Characteristic         | Symbol  | Min.                              | Max.                              | Unit |
|------------------------|---------|-----------------------------------|-----------------------------------|------|
| Core Supply Voltage    | VDDC    | -0.3                              | 1.5                               | V    |
| I/O Supply Voltage     | VDDIO   | -0.3                              | 5.0                               |      |
| Battery Supply Voltage | VBATT   | -0.3                              | 5.0                               |      |
| Digital Input Voltage  | VIN     | -0.3                              | VDDIO                             |      |
| Analog Input Voltage   | VESDHBM | -0.3                              | 1.5                               |      |
| ESD Human Body Model   |         | -1000, -2000<br>(see notes below) | +1000, +2000<br>(see notes below) |      |
| Storage Temperature    | TA      | -65                               | 150                               | °C   |
| Junction Temperature   |         |                                   | 125                               |      |
| RF input power max     |         |                                   | 23                                | dBm  |

- Notes:
1.  $V_{IN}$  corresponds to all the digital pins.
  2.  $V_{AIN}$  corresponds to the following analog pins: VDD\_RF\_RX, VDD\_RF\_TX, VDD\_AMS, RFIOP, RFION, XO\_N, XO\_P, VDD\_SXDIG, VDD\_VCO.
  3. For  $V_{ESDHBM}$ , each pin is classified as Class 1, or Class 2, or both:
    - The Class 1 pins include all the pins (both analog and digital)
    - The Class 2 pins are all digital pins only
    - $V_{ESDHBM}$  is  $\pm 1kV$  for Class1 pins.  $V_{ESDHBM}$  is  $\pm 2kV$  for Class2 pins

### 4.2 Recommended Operating Conditions

Table 4-2. Recommended Operating Conditions

| Characteristics        | Symbol | Min. | Typ. | Max. | Unit |
|------------------------|--------|------|------|------|------|
| I/O Supply Voltage     | VDDIO  | 2.7  | 3.3  | 3.6  | V    |
| Battery Supply Voltage | VBATT  | 3.0  | 3.6  | 4.2  |      |
| Operating Temperature  |        | -40  |      | 85   | °C   |

- Notes:
1. I/O supply voltage is applied to the following pins: VDDIO\_A, VDDIO.
  2. Battery supply voltage is applied to following pins: VDD\_BATT\_PPA, VDD\_BATT\_PA, VBATT\_BUCK.
  3. Refer to Section 9.1 and Table 9-3 for the details of power connections.

## 4.3 DC Electrical Characteristics

Table 4-3 provides the DC characteristics for the ATWINC1500B digital pads.

**Table 4-3. Electrical Characteristics**

| Characteristic                                     | Min.       | Typ. | Max.       | Unit |
|--|------------|------|------------|------|
| Input Low Voltage $V_{IL}$                         | -0.30      |      | 0.65       | V    |
| Input High Voltage $V_{IH}$                        | VDDIO-0.60 |      | VDDIO+0.30 |      |
| Output Low Voltage $V_{OL}$                        |            |      | 0.45       |      |
| Output High Voltage $V_{OH}$                       | VDDIO-0.50 |      |            |      |
| Output Loading                                     |            |      | 20         | pF   |
| Digital Input Load                                 |            |      | 6          |      |
| Pad Drive Strength (regular pads <sup>1</sup> )    | 8          | 13.5 |            | mA   |
| Pad Drive Strength (high-drive pads <sup>1</sup> ) | 16         | 27   |            |      |

Note: 1. The following are high-drive pads: I2C\_SCL, I2C\_SDA; all other pads are regular.

## 5 Clocking

### 5.1 Crystal Oscillator

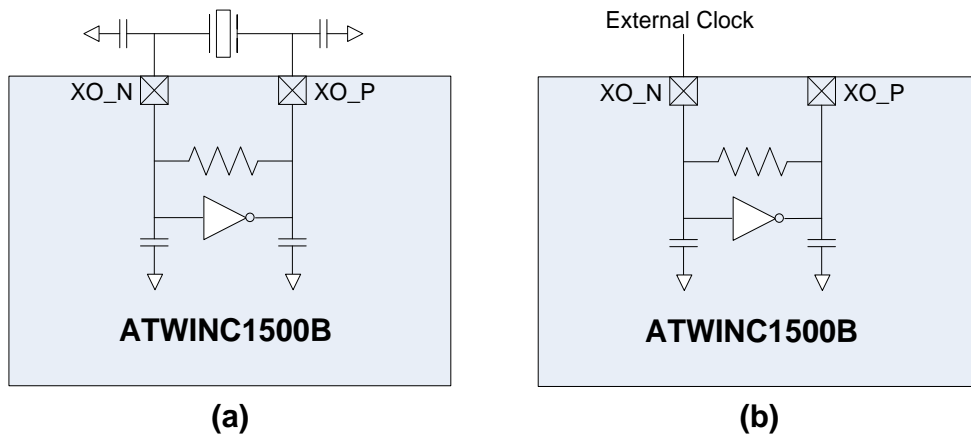
**Table 5-1. Crystal Oscillator Parameters**

| Parameter                               | Min. | Typ. | Max. | Unit     |
|---|------|------|------|----------|
| Crystal Resonant Frequency              | 12   | 26   | 40   | MHz      |
| Crystal Equivalent Series Resistance    |      | 50   | 150  | $\Omega$ |
| Stability – Initial Offset <sup>1</sup> | -100 |      | 100  | ppm      |
| Stability - Temperature and Aging       | -25  |      | 25   |          |

Note: 1. Initial offset must be calibrated to maintain  $\pm 25$ ppm in all operating conditions. This calibration is performed during final production testing.

The block diagram in Figure 5-1(a) shows how the internal Crystal Oscillator (XO) is connected to the external crystal. The XO has 5pF internal capacitance on each terminal XO\_P and XO\_N. To bypass the crystal oscillator with an external reference, an external signal capable of driving 5pF can be applied to the XO\_N terminal as shown Figure 5-1(b).

**Figure 5-1. XO Connections**



(a) Crystal Oscillator is Used

(b) Crystal Oscillator is Bypassed

Table 5-2 specifies the electrical and performance requirements for the external clock.

**Table 5-2. Bypass Clock Specification**

| Parameter                         | Min. | Max.   | Unit   | Comments   |
|-----------------------------------|------|--------|--------|--|
| Oscillation frequency             | 12   | 32     | MHz    | Must be able to drive 5pF load @ desired frequency         |
| Voltage swing                     | 0.5  | 1.2    | Vpp    | Must be AC coupled   |
| Stability – Temperature and Aging | -25  | +25    | ppm    |  |
| Phase Noise                       |      | -130   | dBc/Hz | At 10kHz offset  |
| Jitter(RMS)                       |      | <1psec |        | Based on integrated phase noise spectrum from 1kHz to 1MHz |

## 5.2 Low Power Oscillator

ATWINC1500B has an internally-generated 32kHz clock to provide timing information for various sleep functions. Alternatively, ATWINC1500B allows for an external 32kHz clock to be used for this purpose, which is provided through Pin 24 (RTC\_CLK). Software selects whether the internal clock or external clock is used.

The internal low-power clock is ring-oscillator based and has accuracy within 10,000ppm. When using the internal low-power clock, the advance wakeup time in beacon monitoring mode has to be increased by about 1% of the sleep time to compensate for the oscillator inaccuracy. For example, for the DTIM interval value of 1, wakeup time has to be increased by 1ms.

For any application targeting very low power consumption, an external 32kHz RTC clock should be used.

## 6 CPU and Memory Subsystems

### 6.1 Processor

ATWINC1500B has a Cortus APS3 32-bit processor. This processor performs many of the MAC functions, including but not limited to association, authentication, power management, security key management, and MSDU aggregation/de-aggregation. In addition, the processor provides flexibility for various modes of operation, such as STA and AP modes.

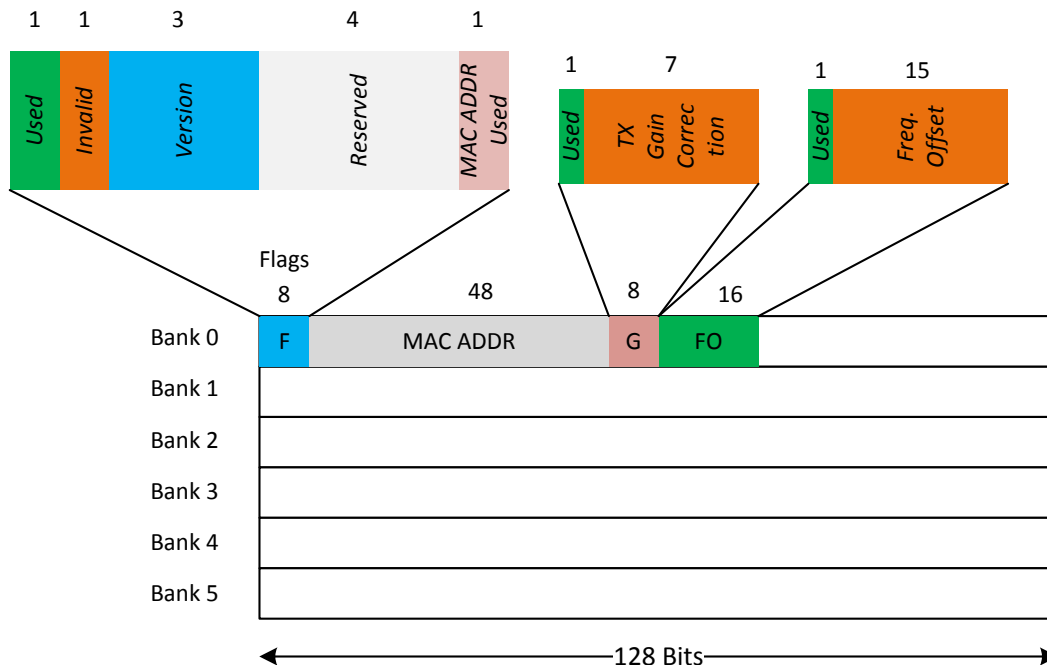
### 6.2 Memory Subsystem

The APS3 core uses a 128KB instruction/boot ROM along with a 160KB instruction RAM and a 64KB data RAM. ATWINC1500B also has 4Mb of Flash memory, which can be used for system software. In addition, the device uses a 128KB shared RAM, accessible by the processor and MAC, which allows the APS3 core to perform various data management tasks on the TX and RX data packets.

### 6.3 Non-volatile Memory (eFuse)

ATWINC1500B has 768 bits of non-volatile eFuse memory that can be read by the CPU after device reset. This non-volatile one-time-programmable (OTP) memory can be used to store customer-specific parameters, such as MAC address; various calibration information, such as TX power, crystal frequency offset, etc.; and other software-specific configuration parameters. The eFuse is partitioned into six 128-bit banks. Each bank has the same bit map, which is shown in Figure 6-1. The purpose of the first 80 bits in each bank is fixed, and the remaining 48 bits are general-purpose software dependent bits, or reserved for future use. Since each bank can be programmed independently, this allows for several updates of the device parameters following the initial programming, e.g. updating MAC address. Refer to ATWINC1500B Programming Guide for the eFuse programming instructions.

Figure 6-1. eFuse Bit Map



## 7 WLAN Subsystem

The WLAN subsystem is composed of the Media Access Controller (MAC) and the Physical Layer (PHY). The following two subsections describe the MAC and PHY in detail.

### 7.1 MAC

#### 7.1.1 Features

The ATWINC1500B IEEE 802.11 MAC supports the following functions:

- IEEE 802.11b/g/n
- IEEE 802.11e WMM QoS EDCA/PCF multiple access categories traffic scheduling
- Advanced IEEE 802.11n features:
  - Transmission and reception of aggregated MPDUs (A-MPDU)
  - Transmission and reception of aggregated MSDUs (A-MSDU)
  - Immediate Block Acknowledgement
  - Reduced Interframe Spacing (RIFS)
- Support for IEEE 802.11i and WPA security with key management
  - WEP 64/128
  - WPA-TKIP
  - 128-bit WPA2 CCMP (AES)
- Support for WAPI security
- Advanced power management
  - Standard 802.11 Power Save Mode
  - Wi-Fi Alliance WMM-PS (U-APSD)
- RTS-CTS and CTS-self support
- Supports either STA or AP mode in the infrastructure basic service set mode
- Supports independent basic service set (IBSS)

#### 7.1.2 Description

The ATWINC1500B MAC is designed to operate at low power while providing high data throughput. The IEEE 802.11 MAC functions are implemented with a combination of dedicated datapath engines, hardwired control logic, and a low-power, high-efficiency microprocessor. The combination of dedicated logic with a programmable processor provides optimal power efficiency and real-time response while providing the flexibility to accommodate evolving standards and future feature enhancements.

Dedicated datapath engines are used to implement data path functions with heavy computational requirements. For example, an FCS engine checks the CRC of the transmitting and receiving packets, and a cipher engine performs all the required encryption and decryption operations for the WEP, WPA-TKIP, WPA2 CCMP-AES, and WAPI security requirements.

Control functions which have real-time requirements are implemented using hardwired control logic modules. These logic modules offer real-time response while maintaining configurability via the processor. Examples of hardwired control logic modules are the channel access control module (implements EDCA/HCCA, Beacon TX control, interframe spacing, etc.), protocol timer module (responsible for the Network Access Vector, back-off timing, timing synchronization function, and slot management), MPDU handling module, aggregation/de-aggregation module, block ACK controller (implements the protocol requirements for burst block communication), and TX/RX control FSMs (coordinate data movement between PHY-MAC interface, cipher engine, and the DMA interface to the TX/RX FIFOs).

The MAC functions implemented solely in software on the microprocessor have the following characteristics:

- Functions with high memory requirements or complex data structures. Examples are association table management and power save queuing.
- Functions with low computational load or without critical real-time requirements. Examples are authentication and association.
- Functions which need flexibility and upgradeability. Examples are beacon frame processing and QoS scheduling.

## 7.2 PHY

### 7.2.1 Features

The ATWINC1500B IEEE802.11 PHY supports the following functions:

- Single antenna 1x1 stream in 20MHz channels
- Supports IEEE 802.11b DSSS-CCK modulation: 1, 2, 5.5, 11Mbps
- Supports IEEE 802.11g OFDM modulation: 6, 9, 12, 18, 24, 36, 48, 54Mbps
- Supports IEEE 802.11n HT modulations MCS0-7, 20MHz, 800 and 400ns guard interval: 6.5, 7.2, 13.0, 14.4, 19.5, 21.7, 26.0, 28.9, 39.0, 43.3, 52.0, 57.8, 58.5, 65.0, 72.2Mbps
- IEEE 802.11n mixed mode operation
- Per packet TX power control
- Advanced channel estimation/equalization, automatic gain control, CCA, carrier/symbol recovery, and frame detection

### 7.2.2 Description

The ATWINC1500B WLAN PHY is designed to achieve reliable and power-efficient physical layer communication specified by IEEE 802.11b/g/n in single stream mode with 20MHz bandwidth. Advanced algorithms have been employed to achieve maximum throughput in a real world communication environment with impairments and interference. The PHY implements all the required functions such as FFT, filtering, FEC (Viterbi decoder), frequency and timing acquisition and tracking, channel estimation and equalization, carrier sensing and clear channel assessment, as well as the automatic gain control.

## 7.3 Radio

### 7.3.1 Receiver Performance

Radio Performance under Typical Conditions: VBATT=3.6V; VDDIO=3.3V; temp.: 25°C.

**Table 7-1. Receiver Performance**

| Parameter              | Description | Min.  | Typ. | Max.  | Unit |
|------------------------|-------------|-------|------|-------|------|
| Frequency              |             | 2,412 |      | 2,484 | MHz  |
| Sensitivity<br>802.11b | 1Mbps DSS   |       | -98  |       | dBm  |
|                        | 2Mbps DSS   |       | -94  |       |      |
|                        | 5.5Mbps DSS |       | -92  |       |      |
|                        | 11Mbps DSS  |       | -88  |       |      |
| Sensitivity<br>802.11g | 6Mbps OFDM  |       | -90  |       |      |
|                        | 9Mbps OFDM  |       | -89  |       |      |

| Parameter                            | Description                     | Min. | Typ. | Max. | Unit |
|--------------------------------------|---------------------------------|------|------|------|------|
|                                      | 12Mbps OFDM                     |      | -88  |      | dBm  |
|                                      | 18Mbps OFDM                     |      | -85  |      |      |
|                                      | 24Mbps OFDM                     |      | -83  |      |      |
|                                      | 36Mbps OFDM                     |      | -80  |      |      |
|                                      | 48Mbps OFDM                     |      | -76  |      |      |
|                                      | 54Mbps OFDM                     |      | -74  |      |      |
| Sensitivity<br>802.11n<br>(BW=20MHz) | MCS 0                           |      | -89  |      |      |
|                                      | MCS 1                           |      | -87  |      |      |
|                                      | MCS 2                           |      | -85  |      |      |
|                                      | MCS 3                           |      | -82  |      |      |
|                                      | MCS 4                           |      | -77  |      |      |
|                                      | MCS 5                           |      | -74  |      |      |
|                                      | MCS 6                           |      | -72  |      |      |
| Maximum Receive<br>Signal Level      | 1-11Mbps DSS                    |      | 0    |      |      |
|                                      | 6-54Mbps OFDM                   |      | 0    |      |      |
|                                      | MCS 0 – 7                       |      | 0    |      |      |
| Adjacent Channel Re-<br>jection      | 1Mbps DSS (30MHz offset)        |      | 50   |      | dB   |
|                                      | 11Mbps DSS (25MHz offset)       |      | 43   |      |      |
|                                      | 6Mbps OFDM (25MHz offset)       |      | 40   |      |      |
|                                      | 54Mbps OFDM (25MHz offset)      |      | 25   |      |      |
|                                      | MCS 0 – 20MHz BW (25MHz offset) |      | 40   |      |      |
|                                      | MCS 7 – 20MHz BW (25MHz offset) |      | 20   |      |      |
| Cellular Blocker Im-<br>munity       | 776-794MHz CDMA                 |      | -14  |      | dBm  |
|                                      | 824-849MHz GSM                  |      | -10  |      |      |
|                                      | 880-915MHz GSM                  |      | -10  |      |      |
|                                      | 1710-1785MHz GSM                |      | -15  |      |      |
|                                      | 1850-1910MHz GSM                |      | -15  |      |      |
|                                      | 1850-1910MHz WCDMA              |      | -24  |      |      |
|                                      | 1920-1980MHz WCDMA              |      | -24  |      |      |

### 7.3.2 Transmitter Performance

Radio Performance under Typical Conditions: VBATT=3.6V; VDDIO=3.3V; temp.: 25°C.

**Table 7-2. Transmitter Performance**

| Parameter                                  | Description     | Min.  | Typ.                | Max.  | Unit   |
|--|-----------------|-------|---------------------|-------|--------|
| Frequency                                  |                 | 2,412 |                     | 2,484 | MHz    |
| Output Power <sup>(1)</sup><br>ON_Transmit | 802.11b 1Mbps   |       | 19.5                |       | dBm    |
|  | 802.11b 11Mbps  |       | 20.5                |       |        |
|  | 802.11g 6Mbps   |       | 19.5                |       |        |
|  | 802.11g 54Mbps  |       | 17.5                |       |        |
|  | 802.11n MCS 0   |       | 18.0                |       |        |
|  | 802.11n MCS 7   |       | 15.5                |       |        |
| TX Power Accuracy                          |                 |       | ±1.5 <sup>(2)</sup> |       | dB     |
| Carrier Suppression                        |                 |       | 30.0                |       | dBc    |
| Harmonic Output Power                      | 2 <sup>nd</sup> |       | -33                 |       | dBm/Hz |
|  | 3 <sup>rd</sup> |       | -38                 |       |        |

- Notes: 1. Measured at 802.11 spec compliant EVM/Spectral Mask.  
 2. Measured at RF Pin assuming 50Ω differential.



## 8 External Interfaces

ATWINC1500B external interfaces include:

- I<sup>2</sup>C Slave for control
- SPI Slave and SDIO Slave for control and data transfer
- I<sup>2</sup>C Master for external EEPROM
- Two UARTs for debug, control, and data transfer
- General Purpose Input/Output (GPIO) pins
- Wi-Fi/Bluetooth coexistence interface

With the exception of the SPI Slave and SDIO Slave host interfaces, which are selected using the dedicated SDIO\_SPI\_CFG pin, the other interfaces can be assigned to various pins by programming the corresponding pin muxing control register for each pin to a specific value between 0 and 6. The default values of these registers are 0, which is GPIO mode. The summary of the available interfaces and their corresponding pin MUX settings is shown in [Table 8-1](#). For specific programming instructions refer to ATWINC1500B Programming Guide.

**Table 8-1. Pin-MUX Matrix of External Interfaces**

| Pin Name            | Mux 0  | Mux 1         | Mux 2             | Mux3        | Mux4              | Mux5          | Mux6   |
|---------------------|--------|---------------|-------------------|-------------|-------------------|---------------|--------|
| GPIO0 / HOST_WAKEUP | GPIO_0 | I_HOST_WAKEUP |                   | O_UART1_TXD | IO_I2C_MASTER_SCL |               | IO_COE |
| GPIO2 / IRQN        | GPIO_2 | O_IRQN        | O_UART1_TXD       | I_UART1_RXD |                   |               | IO_COE |
| SD_DAT3             | GPIO_7 | IO_SD_DAT3    | IO_I2C_MASTER_SCL | O_UART1_TXD |                   | I_HOST_WAKEUP | IO_COE |
| SD_DAT2 / SPI_RXD   |        | IO_SD_DAT2    | I_SPI_RXD         | I_UART1_RXD | O_UART2_TXD       |               |        |
| SD_DAT1 / SPI_SSN   |        | IO_SD_DAT1    | IO_SPI_SSN        |             | O_UART2_RTS       |               |        |
| SD_DAT0 / SPI_TXD   |        | IO_SD_DAT0    | IO_SPI_TXD        |             | I_UART2_RXD       |               |        |
| SD_CMD / SPI_SCK    |        | IO_SD_CMD     | IO_SPI_SCK        |             | I_UART2_CTS       | I_RTC_CLK     |        |
| SD_CLK              | GPIO_8 | I_SD_CLK      | IO_I2C_MASTER_SDA | I_UART1_RXD |                   | O_UART1_TXD   | IO_COE |
| GPIO1 / RTC_CLK     | GPIO_1 | I_RTC_CLK     | O_UART1_TXD       | I_UART1_RXD | IO_I2C_MASTER_SDA |               | IO_COE |
| GPIO_3              | GPIO_3 |               |                   | I_UART1_RXD |                   | O_UART2_RTS   | IO_COE |
| GPIO_4              | GPIO_4 |               | IO_I2C_MASTER_SCL | I_UART2_RXD |                   |               | IO_COE |
| GPIO_5              | GPIO_5 |               | I_HOST_WAKEUP     | O_UART1_TXD |                   | I_UART2_CTS   | IO_COE |
| GPIO_6              | GPIO_6 |               | IO_I2C_MASTER_SDA | O_UART2_TXD |                   |               | IO_COE |
| I2C_SCL             |        | IO_I2C_SCL    | O_UART1_TXD       | I_RTC_CLK   | IO_I2C_MASTER_SCL |               | IO_COE |
| I2C_SDA             |        | IO_I2C_SDA    | I_UART1_RXD       |             | IO_I2C_MASTER_SDA |               | IO_COE |

### 8.1 I<sup>2</sup>C Slave Interface

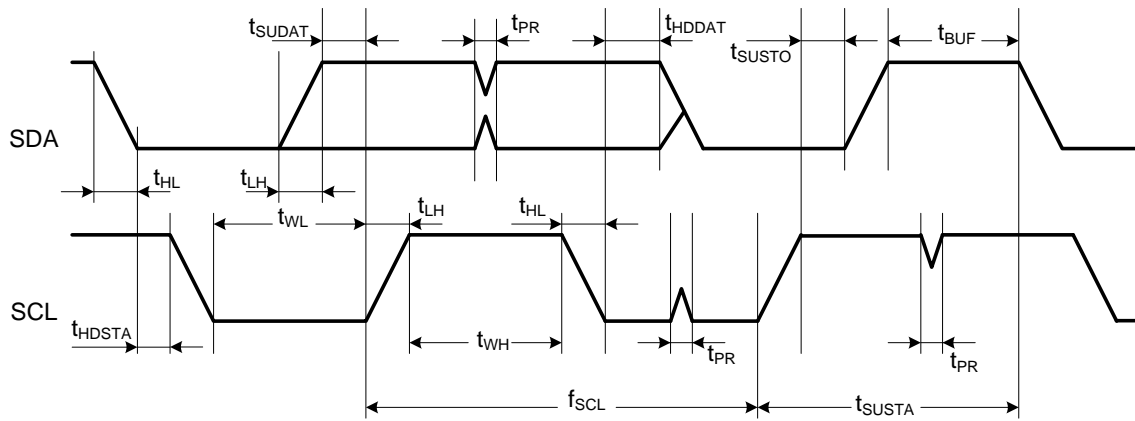
The I<sup>2</sup>C Slave interface, used primarily for control by the host processor, is a two-wire serial interface consisting of a serial data line (SDA, Pin 33) and a serial clock (SCL, Pin 32). It responds to the seven bit address value 0x60. The ATWINC1500B I<sup>2</sup>C supports I<sup>2</sup>C bus Version 2.1 - 2000 and can operate in standard mode (with data rates up to 100Kb/s) and fast mode (with data rates up to 400Kb/s).

The I<sup>2</sup>C Slave is a synchronous serial interface. The SDA line is a bidirectional signal and changes only while the SCL line is low, except for STOP, START, and RESTART conditions. The output drivers are open-drain to perform wire-AND functions on the bus. The maximum number of devices on the bus is limited by only the maximum capacitance specification of 400pF. Data is transmitted in byte packages.

For specific information, refer to the Philips Specification entitled “The I<sup>2</sup>C -Bus Specification, Version 2.1”.

The I<sup>2</sup>C Slave timing is provided in [Figure 8-1](#) and [Table 8-2](#).

**Figure 8-1. I<sup>2</sup>C Slave Timing Diagram**



**Table 8-2. I<sup>2</sup>C Slave Timing Parameters**

| Parameter                            | Symbol      | Min. | Max. | Units   | Remarks                                 |
|--------------------------------------|-------------|------|------|---------|---|
| SCL Clock Frequency                  | $f_{SCL}$   | 0    | 400  | kHz     |   |
| SCL Low Pulse Width                  | $t_{WL}$    | 1.3  |      | $\mu s$ |   |
| SCL High Pulse Width                 | $t_{WH}$    | 0.6  |      |         |   |
| SCL, SDA Fall Time                   | $t_{HL}$    |      | 300  | ns      | This is dictated by external components |
| SCL, SDA Rise Time                   | $t_{LH}$    |      | 300  |         |   |
| START Setup Time                     | $t_{SUSTA}$ | 0.6  |      | $\mu s$ |   |
| START Hold Time                      | $t_{HDSTA}$ | 0.6  |      |         |   |
| SDA Setup Time                       | $t_{SUDAT}$ | 100  |      | ns      | Slave and Master Default                |
| SDA Hold Time                        | $t_{HDDAT}$ | 0    |      |         |   |
|                                      |             | 40   |      |         | Master Programming Option               |
| STOP Setup time                      | $t_{SUSTO}$ | 0.6  |      | $\mu s$ |   |
| Bus Free Time Between STOP and START | $t_{BUF}$   | 1.3  |      |         |   |
| Glitch Pulse Reject                  | $t_{PR}$    | 0    | 50   | ns      |   |

## 8.2 I<sup>2</sup>C Master Interface

ATWINC1500B provides an I<sup>2</sup>C bus master, which is intended primarily for accessing an external EEPROM memory through a software-defined protocol. The I<sup>2</sup>C Master is a two-wire serial interface consisting of a serial data line (SDA) and a serial clock line (SCL). SDA can be configured on one of the following pins: SD\_CLK (pin 19), GPIO1 (pin 24), GPIO6 (pin 31), or I2C\_SDA (pin 33). SCL can be configured on one of the following pins: GPIO0 (pin 10), SD\_DAT3 (pin 12), GPIO4 (pin 29), or I2C\_SCL (pin 32). For more specific instructions refer to ATWINC1500B Programming Guide.

The I<sup>2</sup>C Master interface supports three speeds:

- Standard mode (100kb/s)
- Fast mode (400kb/s)
- High-speed mode (3.4Mb/s)

The timing diagram of the I<sup>2</sup>C Master interface is the same as that of the I<sup>2</sup>C Slave interface (see [Figure 8-1](#)). The timing parameters of I<sup>2</sup>C Master are shown in [Table 8-3](#).

**Table 8-3. I<sup>2</sup>C Master Timing Parameters**

| Parameter                            | Symbol             | Standard Mode |      | Fast Mode |      | High-Speed Mode |      | Units |
|--------------------------------------|--------------------|---------------|------|-----------|------|-----------------|------|-------|
|                                      |                    | Min.          | Max. | Min.      | Max. | Min.            | Max. |       |
| SCL Clock Frequency                  | f <sub>SCL</sub>   | 0             | 100  | 0         | 400  | 0               | 3400 | kHz   |
| SCL Low Pulse Width                  | t <sub>WL</sub>    | 4.7           |      | 1.3       |      | 0.16            |      | μs    |
| SCL High Pulse Width                 | t <sub>WH</sub>    | 4             |      | 0.6       |      | 0.06            |      |       |
| SCL Fall Time                        | t <sub>HLSCL</sub> |               | 300  |           | 300  | 10              | 40   | ns    |
| SDA Fall Time                        | t <sub>HLSDA</sub> |               | 300  |           | 300  | 10              | 80   |       |
| SCL Rise Time                        | t <sub>LHSCl</sub> |               | 1000 |           | 300  | 10              | 40   |       |
| SDA Rise Time                        | t <sub>LHSDA</sub> |               | 1000 |           | 300  | 10              | 80   |       |
| START Setup Time                     | t <sub>SUSTA</sub> | 4.7           |      | 0.6       |      | 0.16            |      | μs    |
| START Hold Time                      | t <sub>HDSTA</sub> | 4             |      | 0.6       |      | 0.16            |      |       |
| SDA Setup Time                       | t <sub>SUDAT</sub> | 250           |      | 100       |      | 10              |      | ns    |
| SDA Hold Time                        | t <sub>HDDAT</sub> | 5             |      | 40        |      | 0               | 70   |       |
| STOP Setup time                      | t <sub>SUSTO</sub> | 4             |      | 0.6       |      | 0.16            |      | μs    |
| Bus Free Time Between STOP and START | t <sub>BUF</sub>   | 4.7           |      | 1.3       |      |                 |      |       |
| Glitch Pulse Reject                  | t <sub>PR</sub>    |               |      | 0         | 50   |                 |      | ns    |

## 8.3 SPI Slave Interface

ATWINC1500B provides a Serial Peripheral Interface (SPI) that operates as a SPI slave. The SPI Slave interface can be used for control and for serial I/O of 802.11 data. The SPI Slave pins are mapped as shown in [Table 8-4](#). The RXD pin is same as Master Output, Slave Input (MOSI), and the TXD pin is same as Master Input, Slave Output (MISO). The SPI Slave is a full-duplex slave-synchronous serial interface that is available immediately following reset when pin 9 (SDIO\_SPI\_CFG) is tied to VDDIO.

**Table 8-4. SPI Slave Interface Pin Mapping**

| Pin # | SPI Function                     |
|-------|----------------------------------|
| 9     | CFG: Must be tied to VDDIO       |
| 16    | SSN: Active Low Slave Select     |
| 18    | SCK: Serial Clock                |
| 13    | RXD: Serial Data Receive (MOSI)  |
| 17    | TXD: Serial Data Transmit (MISO) |

When the SPI is not selected, i.e., when SSN is high, the SPI interface will not interfere with data transfers between the serial-master and other serial-slave devices. When the serial slave is not selected, its transmitted data output is buffered, resulting in a high impedance drive onto the serial master receive line.

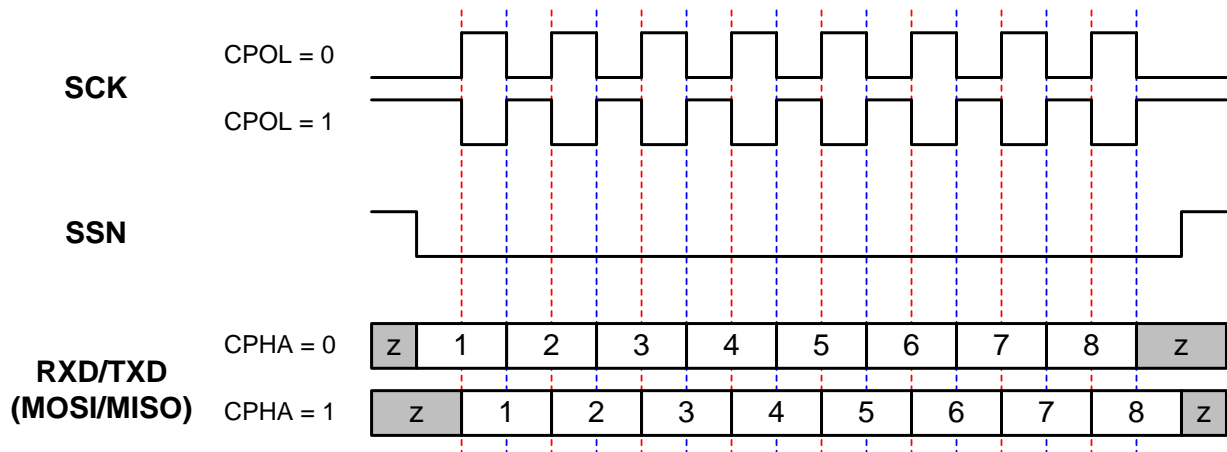
The SPI Slave interface responds to a protocol that allows an external host to read or write any register in the chip as well as initiate DMA transfers. For the details of the SPI protocol and more specific instructions refer to ATWINC1500B Programming Guide.

The SPI Slave interface supports four standard modes as determined by the Clock Polarity (CPOL) and Clock Phase (CPHA) settings. These modes are illustrated in Table 8-5 and Figure 8-2. The red lines in Figure 8-2 correspond to Clock Phase = 0 and the blue lines correspond to Clock Phase = 1.

**Table 8-5. SPI Slave Modes**

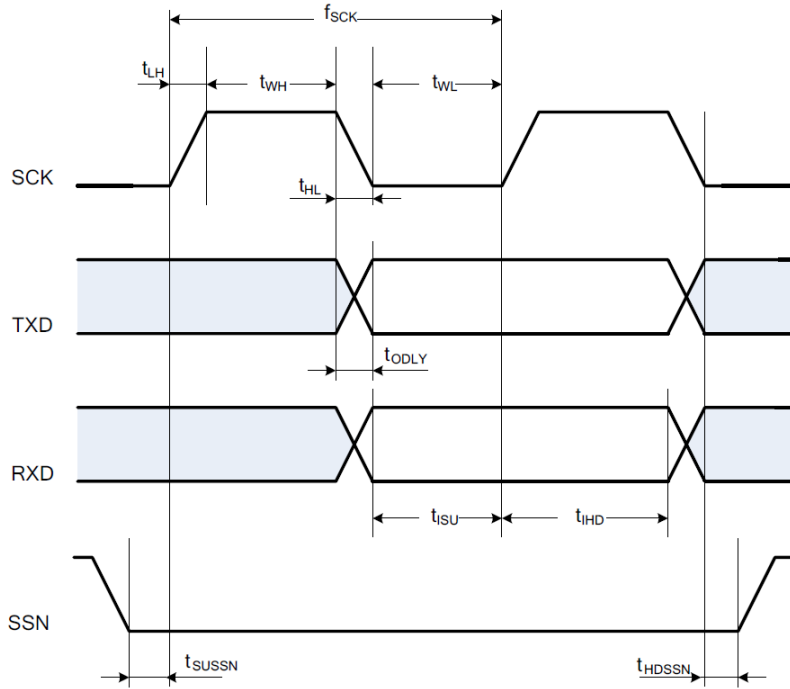
| Mode | CPOL | CPHA |
|------|------|------|
| 0    | 0    | 0    |
| 1    | 0    | 1    |
| 2    | 1    | 0    |
| 3    | 1    | 1    |

**Figure 8-2. SPI Slave Clock Polarity and Clock Phase Timing**



The SPI Slave timing is provided in [Figure 8-3](#) and [Table 8-6](#).

**Figure 8-3. SPI Slave Timing Diagram**



**Table 8-6. SPI Slave Timing Parameters**

| Parameter               | Symbol      | Min. | Max. | Units |
|-------------------------|-------------|------|------|-------|
| Clock Input Frequency   | $f_{SCK}$   |      | 48   | MHz   |
| Clock Low Pulse Width   | $t_{WL}$    | 5    |      | ns    |
| Clock High Pulse Width  | $t_{WH}$    | 5    |      |       |
| Clock Rise Time         | $t_{LH}$    |      | 5    |       |
| Clock Fall Time         | $t_{HL}$    |      | 5    |       |
| Input Setup Time        | $t_{ISU}$   | 5    |      |       |
| Input Hold Time         | $t_{IHD}$   | 5    |      |       |
| Output Delay            | $t_{ODLY}$  | 0    | 20   |       |
| Slave Select Setup Time | $t_{SUSSN}$ | 5    |      |       |
| Slave Select Hold Time  | $t_{HDSSN}$ | 5    |      |       |

## 8.4 UART

ATWINC1500B has two Universal Asynchronous Receiver/Transmitter (UART) interfaces for serial communication: UART1 and UART2. The UARTs are compatible with the RS-232 standard, where ATWINC1500B operates as Data Terminal Equipment (DTE).

UART1 has a 2-pin interface without flow control (RXD/TXD), where RXD (received data) can be enabled on one of five alternative pins and TXD (transmitted data) can be enabled on one of seven alternative pins by programming their corresponding pin MUX control registers (see [Table 8-1](#)). UART2 has a 4-pin interface with flow control (RXD/TXD/CTS/RTS), where RXD (received data) can be enabled on one of two alternative pins, TXD (transmitted data) can be enabled on one of two alternative pins, CTS (clear to send) can be enabled on one of two alternative pins, and RTS (request to send) can be enabled on one of two alternative pins by programming their corresponding pin MUX control registers (see [Table 8-1](#)).

Both UARTs feature programmable baud rate generation with fractional clock division, which allows transmission and reception at a wide variety of standard and non-standard baud rates. The UART input clock is selectable between  $XO \times 2$ ,  $XO$ ,  $XO \div 2$ , and  $XO \div 4$ , which corresponds to 52MHz, 26MHz, 13MHz, and 6.5MHz for the typical  $XO$  frequency (26MHz). The clock divider value is programmable as 13 integer bits and 3 fractional bits (with 8.0 being the smallest recommended value for normal operation). This results in the maximum baud rate of  $52\text{MHz}/8.0 = 6.5\text{Mbd}$  for typical  $XO$  frequency.

Both UARTs can be configured for seven or eight bit operation, with or without parity, with four different parity types (odd, even, mark, or space), and with one or two stop bits. They also have RX and TX FIFOs, which ensure reliable high speed reception and low software overhead transmission. FIFO size is 4x8 for both RX and TX direction. The UARTs also have status registers showing the number of received characters available in the FIFO and various error conditions, as well the ability to generate interrupts based on these status bits.



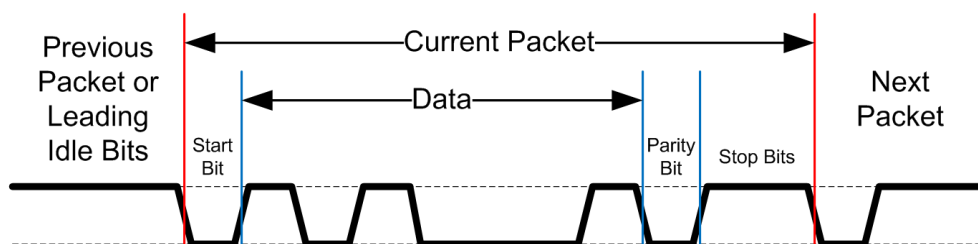
**The RTS and CTS are used for hardware flow control; they MUST be connected to the host MCU UART and enabled for the UART interface to be functional.**

UART2 supports standard flow control using CTS and RTS signals – UART2 can be programmed to enable or disable flow control. CTS is an active low input. When it is asserted (low) UART2 will transmit data; when it becomes de-asserted (high) UART2 will finish transmitting the current byte (if it is in progress) and will not resume transmitting until CTS becomes asserted again. RTS is an active low output. It becomes asserted (low) when the RX FIFO in UART2 has space; it becomes de-asserted (high) when there is not enough space in the RX FIFO.

An example of UART receiving or transmitting a single packet is shown in [Figure 8-4](#). This example shows 7-bit data (0x45), odd parity, and two stop bits.

For more specific instructions refer to ATWINC1500B Programming Guide.

**Figure 8-4. Example of UART RX or TX Packet**



## 8.5 Wi-Fi/Bluetooth Coexistence

ATWINC1500 supports 2-wire and 3-wire Wi-Fi/Bluetooth Coexistence signaling conforming to the IEEE 802.15.2-2003 standard, Part 15.2. The type of coexistence interface used (2 or 3 wire) is chosen to be compatible with the specific Bluetooth device used in a given application. Coexistence interface can be enabled on several alternative pins by programming their corresponding pin MUX control register to 6 (see [Table 8-1](#), where any pin marked “IO\_COE” in the “Mux6” column can be configured for any function of the coexistence interface). [Table 8-7](#) shows a usage example of the 2-wire interface using the GPIO3 and GPIO4 pins; 3-wire interface using the GPIO3, GPIO4, and GPIO5 pins; for more specific instructions on configuring Coexistence refer to ATWINC1500 Programming Guide.

**Table 8-7. Coexistence Pin Assignment Example**

| Pin Name | Pin # | Function | Target   | 2-wire   | 3-wire   |
|----------|-------|----------|--|----------|----------|
| GPIO3    | 28    | BT_Req   | BT is requesting to access the medium to transmit or receive. Goes high on TX or RX slot.            | Used     | Used     |
| GPIO4    | 29    | WL_Act   | Device response to the BT request. High - BT_req is denied and BT slot blocked.                      | Used     | Used     |
| GPIO5    | 30    | BT_Pri   | Priority of the BT packets in the requested slot. High to indicate high priority and low for normal. | Not Used | Used     |
| GPIO6    | 31    | Ant_SW   | Direct control on Antenna (coex bypass).   | Optional | Optional |

## 8.6 GPIOs

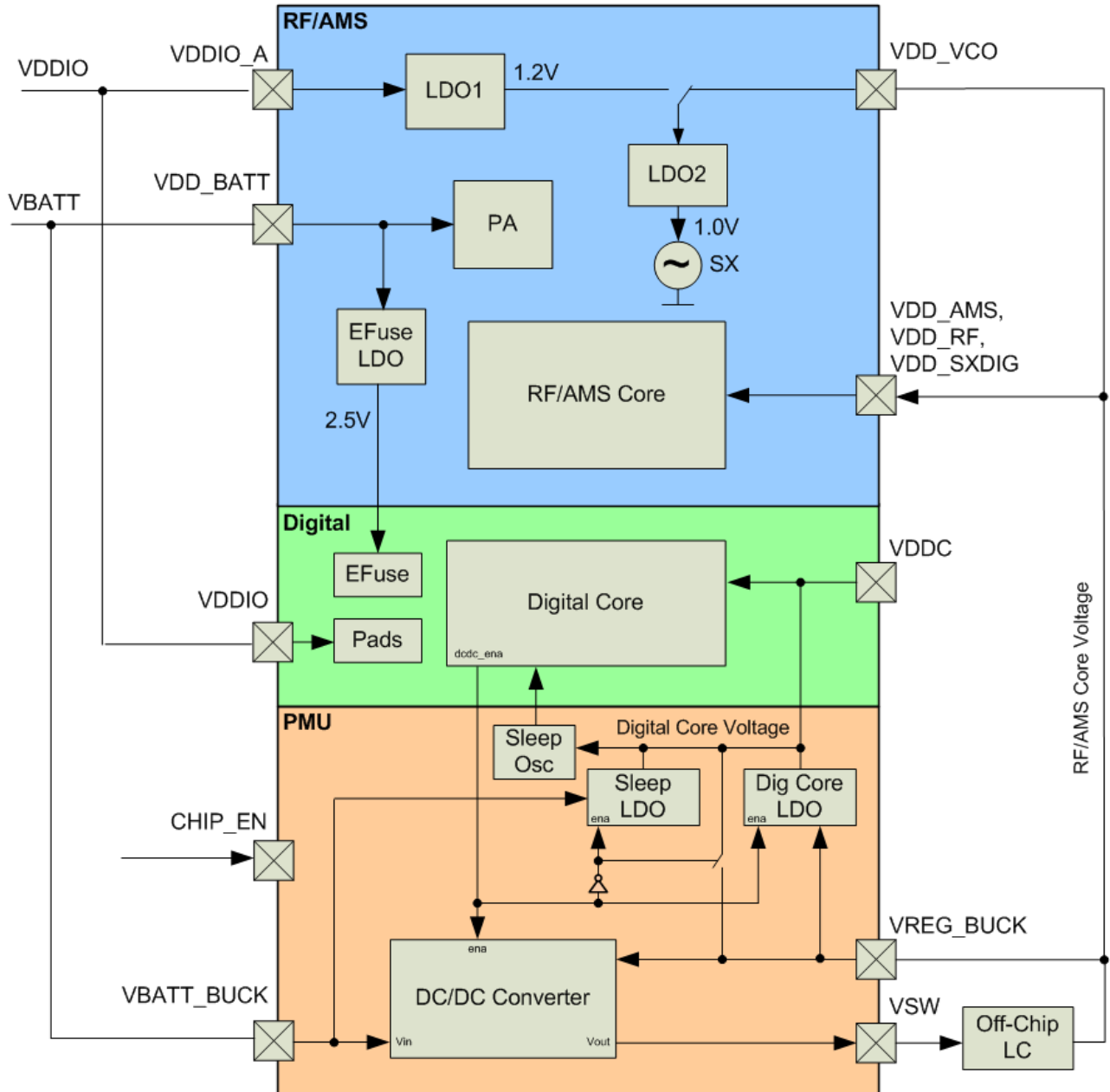
Nine General Purpose Input/Output (GPIO) pins, labeled GPIO 0-8, are available to allow for application specific functions. Each GPIO pin can be programmed as an input (the value of the pin can be read by the host or internal processor) or as an output (the output values can be programmed by the host or internal processor), where the default mode after power-up is input. GPIOs 7 and 8 are only available when the host does not use the SDIO interface, which shares two of its pins with these GPIOs. Therefore, for SDIO-based applications, seven GPIOs (0-6) are available. For more specific usage instructions refer to ATWINC1500B Programming Guide.

# 9 Power Management

## 9.1 Power Architecture

ATWINC1500B uses an innovative power architecture to eliminate the need for external regulators and reduce the number of off-chip components. This architecture is shown in Figure 9-1. The Power Management Unit (PMU) has a DC/DC Converter that converts VBATT to the core supply used by the digital and RF/AMS blocks. Table 9-1 shows the typical values for the digital and RF/AMS core voltages. The PA and eFuse are supplied by dedicated LDOs, and the VCO is supplied by a separate LDO structure.

Figure 9-1. Power Architecture





**Table 9-1. PMU Output Voltages**

| Parameter                       | Typical |
|---------------------------------|---------|
| RF/AMS Core Voltage (VREG_BUCK) | 1.35V   |
| Digital Core Voltage (VDDC)     | 1.10V   |

The power connections in [Figure 9-1](#) provide a conceptual framework for understanding the ATWINC1500B power architecture. Refer to the reference design in [Chapter 10](#) for an example of power supply connections, including proper isolation of the supplies used by the digital and RF/AMS blocks.

## 9.2 Power Consumption

### 9.2.1 Description of Device States

ATWINC1500B has several Devices States:

- ON\_Transmit – Device is actively transmitting an 802.11 signal. Highest output power and nominal current consumption
- ON\_Receive – Device is actively receiving an 802.11 signal. Lowest sensitivity and nominal current consumption
- ON\_Doze – Device is on but is neither transmitting nor receiving
- Power\_Down – Device core supply off (Leakage)
- IDLE connect – Device is connected with 1 DTIM beacon interval

The following pins are used to switch between the ON and Power\_Down states:

- CHIP\_EN – Device pin (pin #23) used to enable DC/DC Converter
- VDDIO – I/O supply voltage from external supply

In the ON states, VDDIO is on and CHIP\_EN is high (at VDDIO voltage level). To switch between the ON states and Power\_Down state CHIP\_EN has to change between high and low (GND) voltage. When VDDIO is off and CHIP\_EN is low, the chip is powered off with no leakage (also see [Section 9.2.3](#)).

### 9.2.2 Current Consumption in Various Device States

**Table 9-2. Current Consumption**

| Device State | Code Rate      | Output Power, dBm | Current Consumption <sup>(1)</sup> |        |
|--------------|----------------|-------------------|------------------------------------|--------|
|              |                |                   | IVBATT                             | IVDDIO |
| ON_Transmit  | 802.11b 1Mbps  | 19.5              | 294 mA                             | 22mA   |
|              | 802.11b 11Mbps | 20.5              | 290 mA                             | 22mA   |
|              | 802.11g 6Mbps  | 19.5              | 292 mA                             | 22mA   |
|              | 802.11g 54Mbps | 17.5              | 250 mA                             | 22mA   |
|              | 802.11n MCS 0  | 18.0              | 289 mA                             | 22mA   |
|              | 802.11n MCS 7  | 15.5              | 244 mA                             | 22mA   |
| ON_Receive   | 802.11b 1Mbps  | N/A               | 52.5mA                             | 22mA   |
|              | 802.11b 11Mbps | N/A               | 52.5mA                             | 22mA   |
|              | 802.11g 6Mbps  | N/A               | 55.0mA                             | 22mA   |

| Device State | Code Rate      | Output Power, dBm | Current Consumption <sup>(1)</sup> |        |
|--------------|----------------|-------------------|------------------------------------|--------|
|              |                |                   | IVBATT                             | IVDDIO |
|              | 802.11g 54Mbps | N/A               | 57.5mA                             | 22mA   |
|              | 802.11n MCS 0  | N/A               | 54.0mA                             | 22mA   |
|              | 802.11n MCS 7  | N/A               | 58.5mA                             | 22mA   |
| ON_Doze      | N/A            | N/A               | 380μA                              | <10μA  |
| Power_Down   | N/A            | N/A               | <0.5μA                             | <3.5μA |

Note: 1. Conditions: VBATT @3.6v, VDDIO @2.8V, 25°C

### 9.2.3 Restrictions for Power States

When no power supplied to the device, i.e., the DC/DC Converter output and VDDIO are both off (at ground potential). In this case, a voltage cannot be applied to the device pins because each pin contains an ESD diode from the pin to supply. This diode will turn on when voltage higher than one diode-drop is supplied to the pin.

If a voltage must be applied to the signal pads while the chip is in a low power state, the VDDIO supply must be on, so the SLEEP or Power\_Down state must be used.

Similarly, to prevent the pin-to-ground diode from turning on, do not apply a voltage that is more than one diode-drop below ground to any pin.

## 9.3 Power-Up/Down Sequence

The power-up/down sequence for ATWINC1500 is shown in Figure 9-2. The timing parameters are provided in Table 9-3.

Figure 9-2. Power Up/Down Sequence

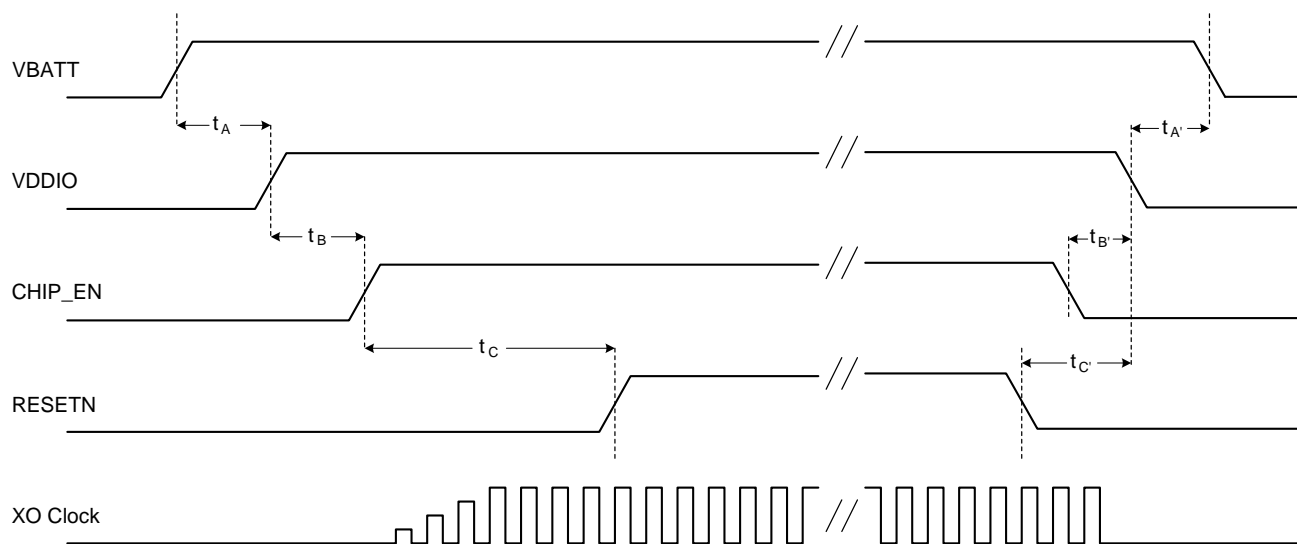


Table 9-3. Power-Up/Down Sequence Timing

| Parameter      | Min. | Max. | Unit | Description              | Notes  |
|----------------|------|------|------|--------------------------|--|
| t <sub>A</sub> | 0    |      | ms   | VBATT rise to VDDIO rise | VBATT and VDDIO can rise simultaneously or can be tied together. VDDIO must not rise before VBATT. |

| Parameter       | Min. | Max. | Unit | Description                  | Notes   |
|-----------------|------|------|------|------------------------------|---|
| t <sub>B</sub>  | 0    |      |      | VDDIO rise to CHIP_EN rise   | CHIP_EN must not rise before VDDIO. CHIP_EN must be driven high or low, not left floating.  |
| t <sub>C</sub>  | 5    |      |      | CHIP_EN rise to RE-SETN rise | This delay is needed because XO clock must stabilize before RESETN removal. RESETN must be driven high or low, not left floating. |
| t <sub>A'</sub> | 0    |      |      | VDDIO fall to VBATT fall     | VBATT and VDDIO can fall simultaneously or can be tied together. VBATT must not fall before VDDIO.                                |
| t <sub>B'</sub> | 0    |      |      | CHIP_EN fall to VDDIO fall   | VDDIO must not fall before CHIP_EN. CHIP_EN and RESETN can fall simultaneously.   |
| t <sub>C'</sub> | 0    |      |      | RESETN fall to VDDIO fall    | VDDIO must not fall before RESETN. RESETN and CHIP_EN can fall simultaneously.  |

## 9.4 Digital I/O Pin Behavior during Power-Up Sequences

Table 9-4 represents digital I/O pin states corresponding to device power modes.

**Table 9-4. Digital I/O Pin Behavior in Different Device States**

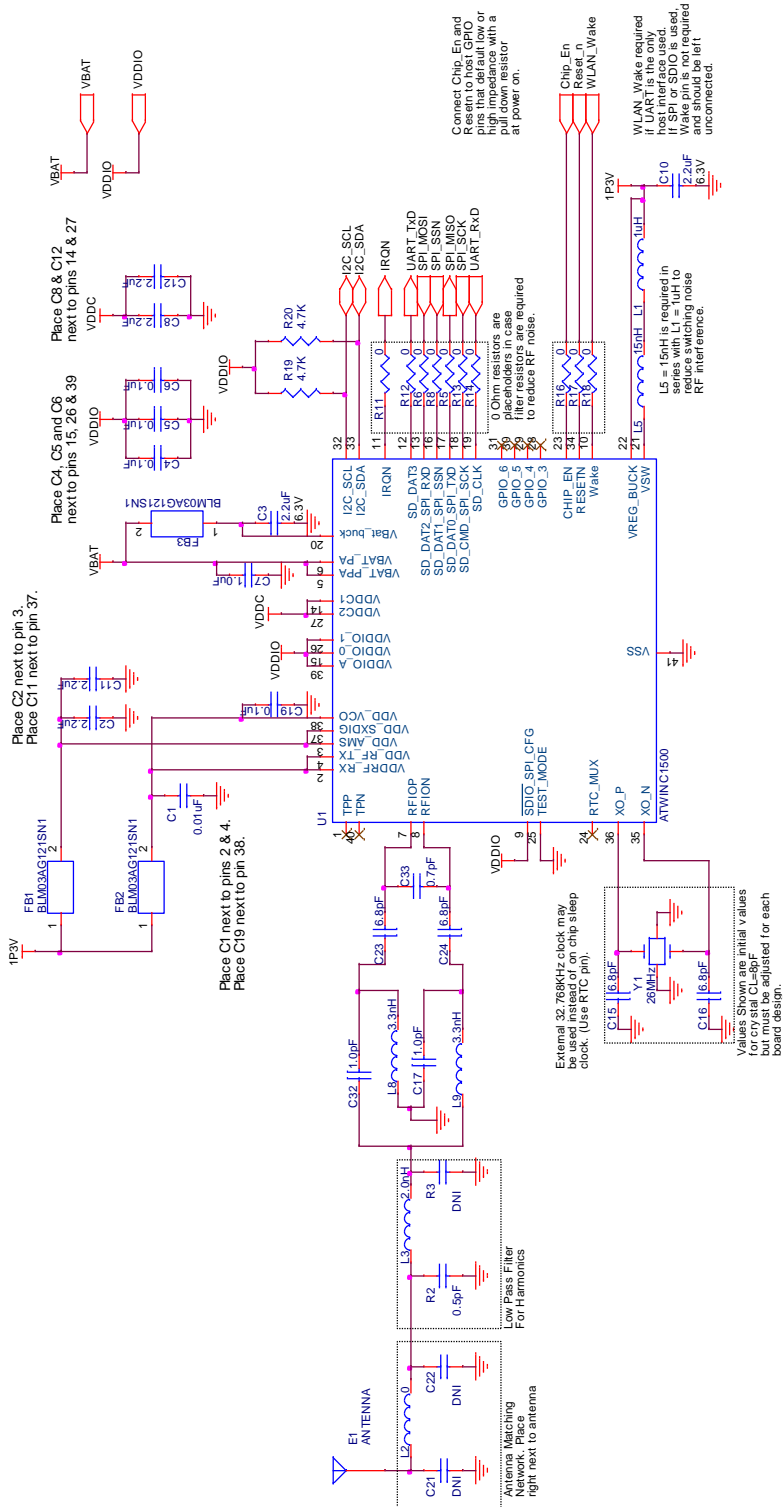
| Device state   | VDDIO | CHIP_EN | RESETN | Output Driver   | Input driver                    | Pull-Up/Down resistor (96kΩ)                             |
|--|-------|---------|--------|---|---------------------------------|--|
| Power_Down:<br>core supply off   | High  | Low     | Low    | Disabled (Hi-Z)   | Disabled                        | Disabled   |
| Power-On Reset:<br>core supply on, hard reset on   | High  | High    | Low    | Disabled (Hi-Z)   | Disabled                        | Enabled  |
| Power-On Default:<br>core supply on, device out of reset but not programmed yet          | High  | High    | High   | Disabled (Hi-Z)   | Enabled                         | Enabled  |
| On_Doze/<br>On_Transmit/<br>On_Receive:<br>core supply on, device programmed by firmware | High  | High    | High   | Programmed by firmware for each pin:<br>Enabled or Disabled | Opposite of Output Driver state | Programmed by firmware for each pin: Enabled or Disabled |

# 10 Reference Design

This chapter provides information on the schematic design the ATWINC1500B.

## 10.1 Reference Schematic

Figure 10-1. ATWINC1500B Reference Schematic



## 10.2 Reference BOM

Figure 10-2. ATWINC1500B Reference BOM

| Item Qty | Reference            | Value         | Description  | Manufacturer       | Part Number                      | Footprint |
|----------|----------------------|---------------|--|--------------------|----------------------------------|-----------|
| 1        | C1                   | 0.01uF        | CAP CER,0.01uF,10%,XSR,0201,10V,-55-125C                     | Murata             | GRM033R61A103RA01D               | 0201      |
| 2        | C2,C3,C8,C10,C11,C12 | 2.2uF         | CAP CER,2.2uF,10%,XSR,0402,6.3V,-55-85C                      | TDK                | C1005XSR0J225K                   | 0402      |
| 3        | C4,C5,C6,C19         | 0.1uF         | CAP CER,0.1uF,10%,XSR,0201,6.3V,-55-125C                     | Murata             | GRM033R60J104KE19D               | 0201      |
| 4        | C7                   | 1.0uF         | CAP CER,1.0uF,10%,XSR,0402,6.3V,-55-85C                      | GRM155R60J105KE19D | GRM155R60J105KE19D               | 0402      |
| 5        | C15,C16,C23,C24      | 6.8pF         | CAP CER,6.8pF,0.5pF,NPO,0201,25V,-55-125C                    | TDK                | CG603CG1E6RBD0308A               | 0201      |
| 6        | C17,C32              | 1.0pF         | CAP CER,1.0pF,0.1pF,NPO,0201,25V,-55-125C                    | Murata             | GRM0335C1E1R0BA01J               | 0201      |
| 7        | C21                  | DNI           | CAP CER,1.0pF,0.1pF,NPO,0201,25V,-55-125C                    | Murata             | GRM0335C1E1R0BA01J               | 0201      |
| 8        | R3,C22               | DNI           | CAP CER,0.5pF,0.1pF,NPO,0201,25V,-55-125C                    | Murata             | 500RGRM0335C1ER50BA0             | 0201      |
| 9        | C33                  | 0.7pF         | CAP CER,0.7pF,0.1pF,NPO,0201,25V,-55-125C                    | Murata             | 500RGRM0335C1ER70BA01D0750R5AV4T | 0201      |
| 10       | E1                   | ANTENNA       | Antenna, 50 ohms, ISM Band, 2.4 - 2.5GHz                     |                    |                                  |           |
| 11       | F81,F82,F83          | BLM03AG121SN1 | FERRITE,120 OHM @100MHz,200mA,0201,-55-125C                  | Murata             | BLM03AG121SN1                    | 0201      |
| 12       | L1                   | 1uH           | POWER INDUCTOR,1uH,20%,940mA,0.125ohms,0603,shielded,-40-85C | Murata             | LQM18PM1R0MFR                    | 0603      |
| 13       | L2                   | 0             | Inductor,2.0nH,0.2nH,Q<13@500MHz,SFR=8.1GHz,0201,-55-125C    | Taiyo Yuden        | HKQ0603S2NOC-T                   | 0201      |
| 14       | L3                   | 2.0nH         | Inductor,2.0nH,0.2nH,Q<13@500MHz,SFR=8.1GHz,0201,-55-125C    | Taiyo Yuden        | HKQ0603S2NOC-T                   | 0201      |
| 15       | L5                   | 15nH          | INDUCTOR,Multilayer,15nH,5%,350mA,Q<9@100MHz,0402            | Murata             | LQG151HS15N10ZD                  | 0402      |
| 16       | L8,L9                | 3.3nH         | Inductor,3.3nH,0.2nH,Q<13@500MHz,SFR=8.1GHz,0201,-55-125C    | Taiyo Yuden        | HKQ0603S3N9C-T                   | 0201      |
| 17       | R2                   | 0.5pF         | CAP CER,0.5pF,0.1pF,NPO,0201,25V,-55-125C                    | Murata             | 500RGRM0335C1ER50BA0             | 0201      |
| 18       | R5,R6,R8,R11,R12,R0  |               | RESISTOR,Thick Film,0 ohm,0201                               | Panasonic          | ERJ-1GNOR00C                     | 0201      |
| 19       | R16,R17,R18          |               |  |                    |                                  |           |
| 19       | R19,R20              | 4.7k          | RESISTOR,Thick Film,4.7k,5%,0201                             | Panasonic          | ERJ-1GEJ472C                     | 0201      |
| 20       | U1                   | ATWINC1500    | IC, WiFi, 40QFN  | Atmel              | ATWINC1500                       | 40QFN     |
| 21       | Y1                   | 26MHz         | CRYSTAL,26MHz,CL=7.36pF,10ppm,-20-85C,ESR=50,3.2x2.5mm       | NDK                | NK3225SA-26.000000MHZ-G3         | 3.2x2.5mm |

ATWINC1500 Reference Design Revised: Friday, February 12, 2016  
 ATWINC1500 Ref Revision: 2

Bill Of Materials February 12, 2016 15:50:06

# 11 Reflow Profile Information

This chapter provides guidelines for reflow processes in getting the Atmel module soldered to the customer's design.

## 11.1 Storage Condition

### 11.1.1 Moisture Barrier Bag Before Opened

A moisture barrier bag must be stored in a temperature of less than 30°C with humidity under 85% RH. The calculated shelf life for the dry-packed product shall be 12 months from the date the bag is sealed.

### 11.1.2 Moisture Barrier Bag Open

Humidity indicator cards must be blue, <30%.

## 11.2 Stencil Design

The recommended stencil is laser-cut, stainless-steel type with thickness of 100µm to 130µm and approximately a 1:1 ratio of stencil opening to pad dimension. To improve paste release, a positive taper with bottom opening 25µm larger than the top can be utilized. Local manufacturing experience may find other combinations of stencil thickness and aperture size to get good results.

## 11.3 Baking Conditions

This module is rated at MSL level 3. After sealed bag is opened, no baking is required within 168 hours so long as the devices are held at ≤30°C/60% RH or stored at <10% RH.

The module will require baking before mounting if:

- The sealed bag has been open for >168 hours
- Humidity Indicator Card reads >10%
- SIPs need to be baked for 8 hours at 125°C

## 11.4 Soldering and Reflow Condition

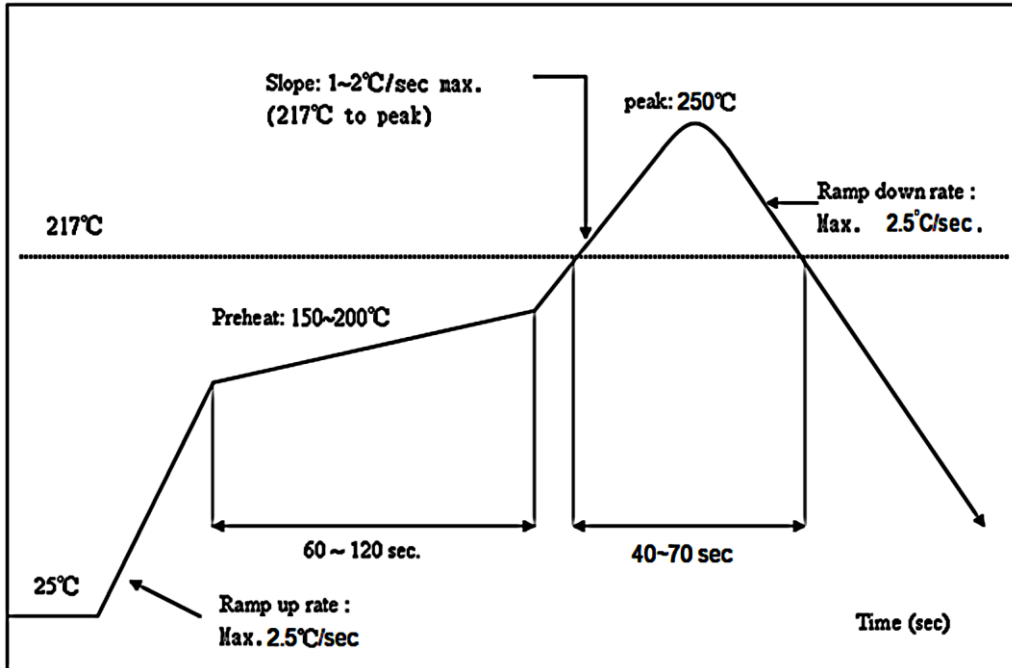
### 11.4.1 Reflow Oven

It is strongly recommended that a reflow oven equipped with more heating zones and Nitrogen atmosphere be used for lead-free assembly. Nitrogen atmosphere has shown to improve the wet-ability and reduce temperature gradient across the board. It can also enhance the appearance of the solder joints by reducing the effects of oxidation.

The following bullet items should also be observed in the reflow process:

- Some recommended pastes include NC-SMQ® 230 flux and Indalloy® 241 solder paste made up of 95.5 Sn/3.8 Ag/0.7 Cu or SENJU N705-GRN3360-K2-V Type 3, no clean paste
- Allowable reflow soldering times: 2 times based on the following reflow soldering profile (see [Figure 11-1](#))
- Temperature profile: Reflow soldering shall be done according to the following temperature profile (see [Figure 11-1](#))
- Peak temp: 250°C

Figure 11-1. Solder Reflow Profile





## 12 Reference Documentation and Support

### 12.1 Reference Documents

Atmel offers a set of collateral documentation to ease integration and device ramp.

The following list of documents available on Atmel web or integrated into development tools.

| Title                          | Content  |
|--------------------------------|--|
| Datasheet                      | This Document  |
| Design Files Package           | User Guide, Schematic, PCB layout, Gerber, BOM and System notes on: RF/Radio Full Test Report, radiation pattern, design guidelines, temperature performance, ESD.   |
| Platform Getting Started Guide | How to use package: Out of the Box starting guide, HW limitations and notes, SW Quick start guidelines.  |
| HW Design Guide                | Best practices and recommendations to design a board with the product, Including: Antenna Design for Wi-Fi (layout recommendations, types of antennas, impedance matching, using a power amplifier etc.), SPI/UART protocol between Wi-Fi SoC and the Host MCU.                    |
| SW Design Guide                | Integration guide with clear description of: High level Arch, overview on how to write a networking application, list all API, parameters and structures.<br>Features of the device, SPI/handshake protocol between device and host MCU, with flow/sequence/state diagram, timing. |
| SW Programmer Guide            | Explain in details the flow chart and how to use each API to implement all generic use cases (e.g. start AP, start STA, provisioning, UDP, TCP, http, TLS, p2p, errors management, connection/recovery mechanism/state diagram) - usage and sample App note                        |

For a complete listing of development-support tools & documentation, visit <http://www.atmel.com/>, or contact the nearest Atmel field representative.

## 13 Revision History

| Doc Rev. | Date    | Comments   |
|----------|---------|--|
| 42487B   | 03/2016 | <ol style="list-style-type: none"> <li>1. Updated device drawing to include note to solder the paddle pad to GND in <a href="#">Figure 3-2</a>.</li> <li>2. Revised table in transmit performance <a href="#">Table 7-2</a>.</li> <li>3. Revised Chapter 9 text and current consumption table information in <a href="#">Table 9-2</a>.</li> <li>4. Updated schematic figure in <a href="#">Figure 10-1</a>.</li> <li>5. Added Schematic BOM in <a href="#">Figure 10-2</a>.</li> <li>6. Added Chapter 11 Reflow Profile Information.</li> <li>7. Added Flow Control note in Section 8.4</li> <li>8. Removed preliminary numbers note from performance numbers <a href="#">Table 9-2</a>.</li> </ol>   |
| 42487A   | 07/2015 | <p>DS update to RevB offering<br/>Changes from WINC1500A (42353D) to WINC1500B:</p> <ol style="list-style-type: none"> <li>1. Added second UART, increased UART data rates</li> <li>2. Increased instruction RAM size from 128KB to 160KB</li> <li>3. Updated pin mux table: added new options for various interfaces</li> <li>4. Improved description of Coexistence interface</li> <li>5. Added VDD_VCO switch and connection in the power architecture</li> <li>6. Updated power consumption numbers</li> <li>7. Updated reference schematic</li> <li>8. Changed RTC_CLK pad definition from pull-down to pull-up</li> <li>9. Changed pin list to add GPIOs 3,4,5,6 - chip pinout identical WINC and WILC</li> <li>10. Added hardware accelerators in feature list (SSL security, IP checksum, OTA security)</li> <li>11. Modified sections 9.2.1 and 9.2.2 to add high-power and low-power modes and current consumption numbers</li> <li>12. Updated radio performance in <a href="#">Table 7-1</a> and <a href="#">Table 7-2</a></li> <li>13. Fixed typos for SPI Slave interface timing in <a href="#">Table 8-6</a></li> <li>14. Fixed typos for battery supply name: changed from VBAT to VBATT</li> <li>15. Corrected <a href="#">Table 8-7</a></li> <li>16. Corrected Power Down and Doze mode current in <a href="#">Table 9-2</a> and in feature list</li> <li>17. Corrected <a href="#">Table 4-3</a> and added high-drive pads reference in <a href="#">Table 3-1</a></li> <li>18. Miscellaneous minor updates and corrections</li> </ol> |



**Atmel Corporation** 1600 Technology Drive, San Jose, CA 95110 USA T: (+1)(408) 441.0311 F: (+1)(408) 436.4200 | [www.atmel.com](http://www.atmel.com)

© 2016 Atmel Corporation. / Rev.: Atmel-42487B-ATWINC1500B-MU\_Datasheet\_03/2016.

Atmel®, Atmel logo and combinations thereof, Enabling Unlimited Possibilities®, and others are registered trademarks or trademarks of Atmel Corporation in U.S. and other countries. ARM®, ARM Connected® logo, and others are the registered trademarks or trademarks of ARM Ltd. Other terms and product names may be trademarks of others.

**DISCLAIMER:** The information in this document is provided in connection with Atmel products. No license, express or implied, by estoppel or otherwise, to any intellectual property right is granted by this document or in connection with the sale of Atmel products. EXCEPT AS SET FORTH IN THE ATMEL TERMS AND CONDITIONS OF SALES LOCATED ON THE ATMEL WEBSITE, ATMEL ASSUMES NO LIABILITY WHATSOEVER AND DISCLAIMS ANY EXPRESS, IMPLIED OR STATUTORY WARRANTY RELATING TO ITS PRODUCTS INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTY OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, OR NON-INFRINGEMENT. IN NO EVENT SHALL ATMEL BE LIABLE FOR ANY DIRECT, INDIRECT, CONSEQUENTIAL, PUNITIVE, SPECIAL OR INCIDENTAL DAMAGES (INCLUDING, WITHOUT LIMITATION, DAMAGES FOR LOSS AND PROFITS, BUSINESS INTERRUPTION, OR LOSS OF INFORMATION) ARISING OUT OF THE USE OR INABILITY TO USE THIS DOCUMENT, EVEN IF ATMEL HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES. Atmel makes no representations or warranties with respect to the accuracy or completeness of the contents of this document and reserves the right to make changes to specifications and products descriptions at any time without notice. Atmel does not make any commitment to update the information contained herein. Unless specifically provided otherwise, Atmel products are not suitable for, and shall not be used in, automotive applications. Atmel products are not intended, authorized, or warranted for use as components in applications intended to support or sustain life.

**SAFETY-CRITICAL, MILITARY, AND AUTOMOTIVE APPLICATIONS DISCLAIMER:** Atmel products are not designed for and will not be used in connection with any applications where the failure of such products would reasonably be expected to result in significant personal injury or death ("Safety-Critical Applications") without an Atmel officer's specific written consent. Safety-Critical Applications include, without limitation, life support devices and systems, equipment or systems for the operation of nuclear facilities and weapons systems. Atmel products are not designed nor intended for use in military or aerospace applications or environments unless specifically designated by Atmel as military-grade. Atmel products are not designed nor intended for use in automotive applications unless specifically designated by Atmel as automotive-grade.

# Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[Microchip:](#)

[ATWINC1500A-MU-T](#) [ATWINC1500A-MU-Y](#) [ATWINC1500B-MU-T](#) [ATWINC1500B-MU-Y](#) [ATWINC1510B-MU-T](#)  
[ATWINC1510B-MU-Y](#)



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



#### Как с нами связаться

**Телефон:** 8 (812) 309 58 32 (многоканальный)

**Факс:** 8 (812) 320-02-42

**Электронная почта:** [org@eplast1.ru](mailto:org@eplast1.ru)

**Адрес:** 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.